

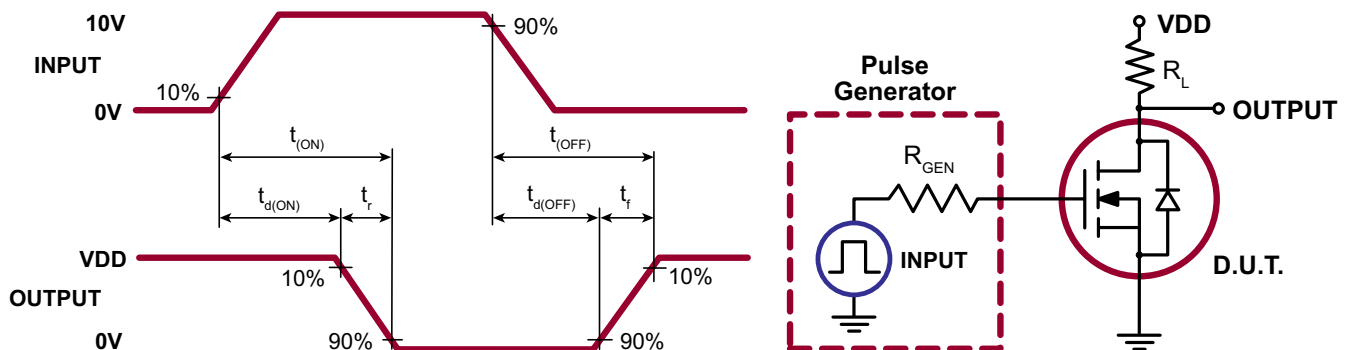
Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Sym	Parameter	Min	Typ	Max	Units	Conditions
BV_{DSS}	Drain-to-source breakdown voltage	240	-	-	V	$V_{GS} = 0V, I_D = 2.0mA$
$V_{GS(th)}$	Gate threshold voltage	0.6	-	2.0	V	$V_{GS} = V_{DS}, I_D = 1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	-5.0	mV/°C	$V_{GS} = V_{DS}, I_D = 1.0mA$
I_{GSS}	Gate body leakage	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
I_{DSS}	Zero gate voltage drain current	-	-	10	μA	$V_{GS} = 0V, V_{DS} = \text{Max Rating}$
		-	-	1.0	mA	$V_{DS} = 0.8\text{Max Rating}, V_{GS} = 0V, T_A = 125^\circ\text{C}$
$I_{D(ON)}$	ON-state drain current	0.5	1.9	-	A	$V_{GS} = 4.5V, V_{DS} = 25V$
		1.0	2.8	-		$V_{GS} = 10V, V_{DS} = 25V$
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	4.0	6.0	Ω	$V_{GS} = 4.5V, I_D = 250mA$
		-	4.0	6.0		$V_{GS} = 10V, I_D = 0.5A$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	1.4	%/°C	$V_{GS} = 10V, I_D = 0.5A$
G_{FS}	Forward transconductance	300	600	-	mmho	$V_{DS} = 20V, I_D = 0.5A$
C_{ISS}	Input capacitance	-	65	125	pF	$V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz$
C_{OSS}	Common source output capacitance	-	35	70		
C_{RSS}	Reverse transfer capacitance	-	10	25		
$t_{d(ON)}$	Turn-on delay time	-	-	10	ns	$V_{DD} = 25V, I_D = 1.0A, R_{GEN} = 25\Omega$
t_r	Rise time	-	-	10		
$t_{d(OFF)}$	Turn-off delay time	-	-	20		
t_f	Fall time	-	-	20		
V_{SD}	Diode forward voltage drop	-	-	1.8	V	$V_{GS} = 0V, I_{SD} = 1.0A$
t_{rr}	Reverse recovery time	-	300	-	ns	$V_{GS} = 0V, I_{SD} = 1.0A$

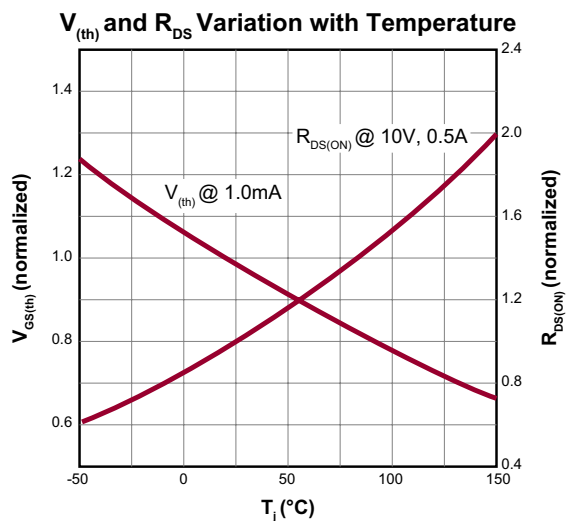
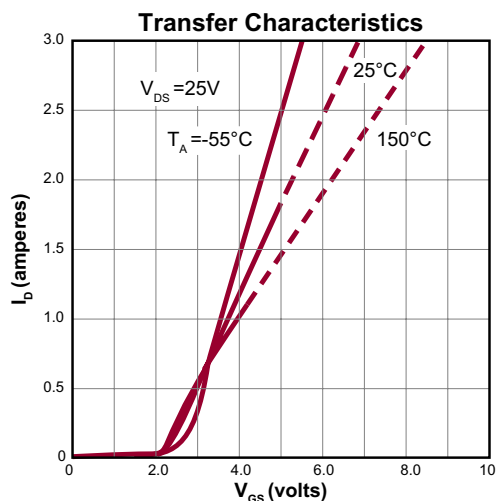
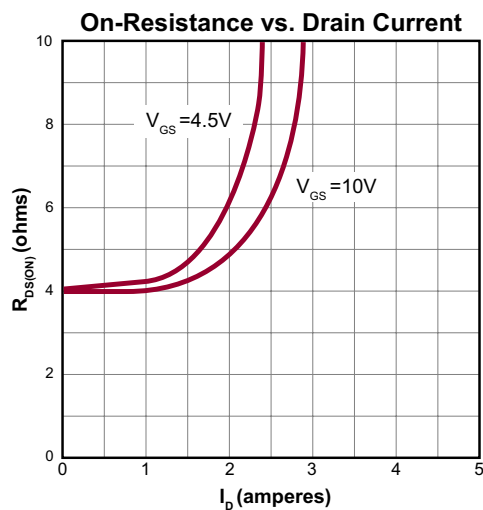
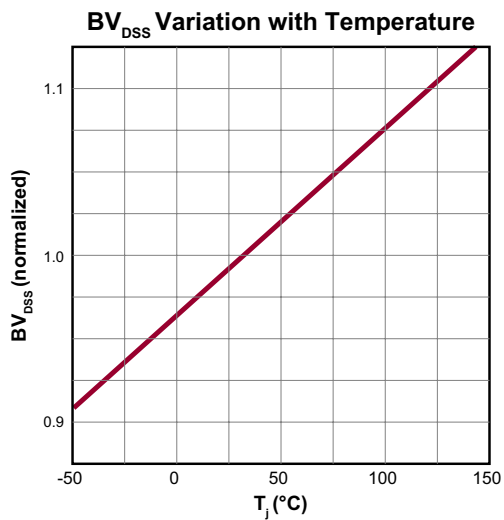
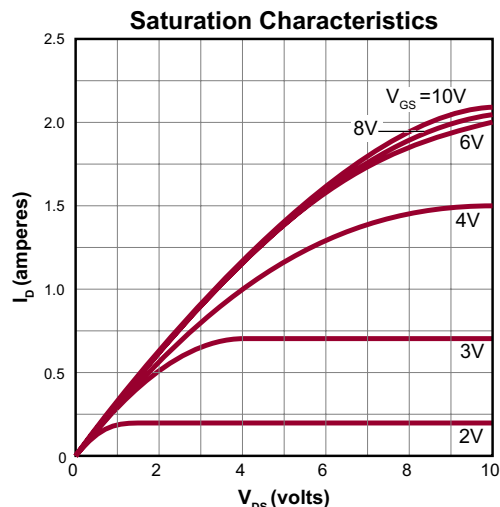
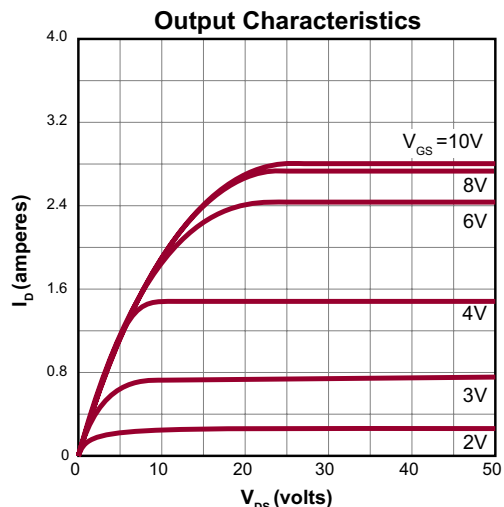
Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300 μs pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

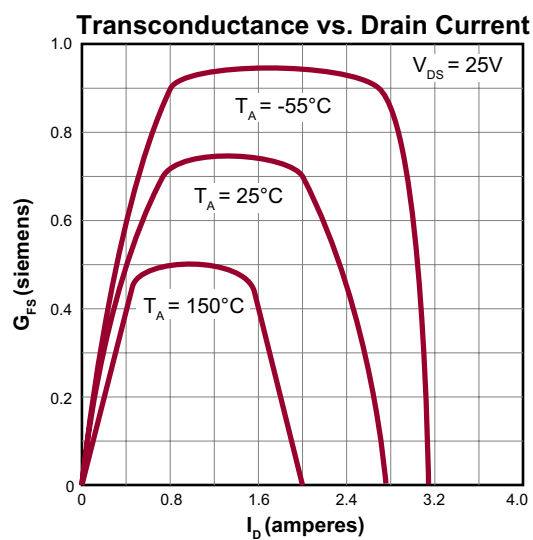
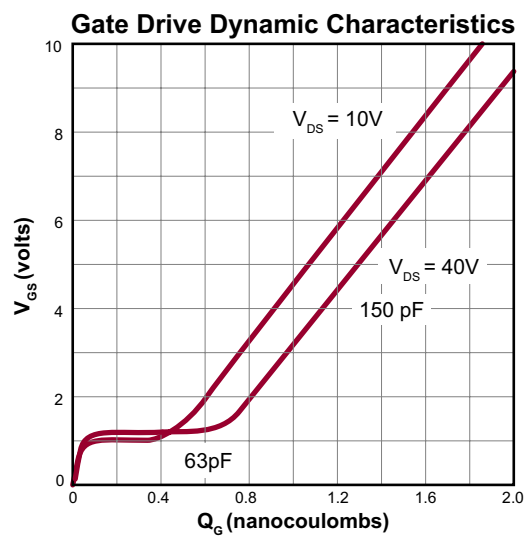
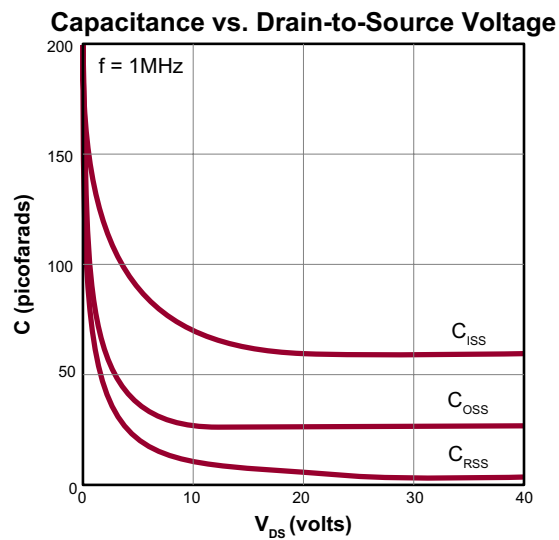
Switching Waveforms and Test Circuit



Typical Performance Curves

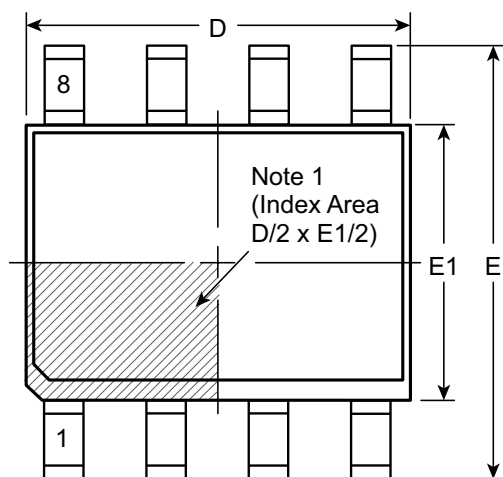


Typical Performance Curves (cont.)

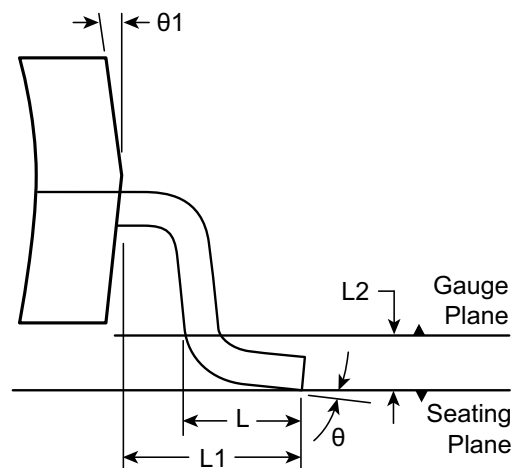


8-Lead SOIC (Narrow Body) Package Outline (TG)

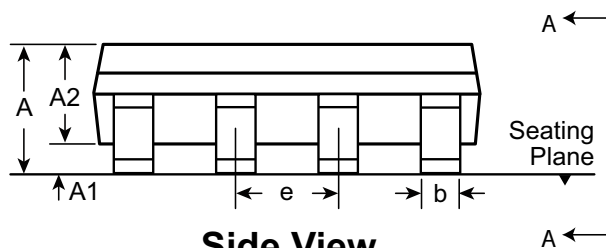
4.90x3.90mm body, 1.75mm height (max), 1.27mm pitch



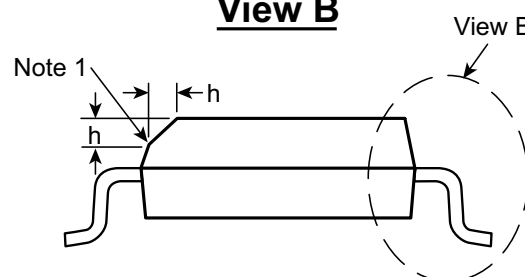
Top View



View B



Side View



View A-A

- Note:**
1. This chamfer feature is optional. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbol		A	A1	A2	b	D	E	E1	e	h	L	L1	L2	θ	θ1
Dimension (mm)	MIN	1.35*	0.10	1.25	0.31	4.80*	5.80*	3.80*	1.27 BSC	0.25	0.40	1.04 REF	0.25 BSC	0°	5°
	NOM	-	-	-	-	4.90	6.00	3.90		-	-			-	-
	MAX	1.75	0.25	1.65*	0.51	5.00*	6.20*	4.00*		0.50	1.27			8°	15°

JEDEC Registration MS-012, Variation AA, Issue E, Sept. 2005.

* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

Supertex Doc. #: DSPD-8SOLGTG, Version I041309.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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